February 14, 2011

Intel Mobile Communications Introduces Advanced Multimode LTE Platform

Compact, Low-Power Solution for Slim Modem Designs Supporting LTE, 3G and 2G

NEUBIBERG, Germany & BARCELONA, Spain--(BUSINESS WIRE)-- Intel Mobile Communications, a leading vendor of advanced mobile semiconductors solutions for handheld devices, today announced the compact multimode (LTE/3G/2G) platform XMM(TM) 7060.

The latest enhancement of the company's comprehensive slim modem portfolio consists of the highly integrated multimode baseband processor X-GOLD™ 706 and the associated multimode RF transceiver SMARTi™ 4G. The chipset is complemented by a robust, full-featured and comprehensively validated 3GPP Release 8 triple mode protocol stack with Inter-Rat features. The new space saving platform is suitable for integration in LTE-enabled portable devices such as mobile handsets, data cards/dongles and other embedded solutions.

LTE is a fast growing market driven by the increasing demand for such mobile broadband services as multimedia broadcasting, music and video streaming and high-speed mobile Internet. It is expected to become the worldwide mobile standard for high-speed Internet due to its high data throughput and high spectral efficiency. However, LTE is faced with the challenge of a strongly fragmented regional frequency landscape. This calls for major RF innovation to create a low-power modem platform that can cover all the diverse frequency plans fitting to portable devices. Intel Mobile Communications is leveraging its proven leadership in RF and meets this challenge by offering the XMM 7060 platform.

"It is our intention to serve this growing market with a compact multimode solution equal to today's 3G PCB footprint," says Prof. Dr. Hermann Eul, president of Intel Mobile Communications. "The slim modem is optimized for low-power operation and has the flexibility to serve up to five LTE bands concurrently with five 3G and four 2G bands, making the dream of a real world-phone come true."

The X-GOLD 706 baseband processor, manufactured in 40nm process technology, is based on the proven 2G/3G X-GOLD™ 626 with an integrated low power LTE L1 subsystem. Therefore smart phones and tablets based on the XMM(TM) 6260 2G/3G platform using the X-GOLD 626 can be easily migrated to LTE ensuring the customers a high degree of reuse of their hardware and software investment. The new baseband processor is accompanied with the SMARTi(TM) 4G, incorporating optimized building blocks of the leading-edge 2G/3G SMARTi™ UE2 and SMARTi™ LU RF transceiver -- the world's first commercially available LTE transceiver. The 65nm CMOS RF transceiver employs a proven digital architecture that significantly reduces the number of external RF components such as power amplifiers and filters, and, hence, reduces board space, BOM and power consumption.

The XMM 7060 slim modem platform fits in less than 700mm(2) PCB (Printed Circuit Board) area including all necessary system components for quad band LTE, penta band 3G and quad band EDGE applications. It supports LTE category 3 (CAT-3) throughputs (100Mbps/50Mbps download/upload respectively) and is compliant to LTE Release 8 standard supporting FDD and TDD mode for all bandwidth up to 20MHz. In addition Inter-RAT handover features with 3G and 2G systems are naturally included.

Availability

First samples of the platform will be available by the third quarter of 2011, with volume shipment scheduled for the second half of 2012. Intel Mobile Communications will present the new XMM 7060 platform on its booth (Hall 1, Booth B22) at the Mobile World Congress in Barcelona (Feb. 14-17).

About Intel Mobile Communications

Intel Mobile Communications develops and markets innovative semiconductor products and solutions for wireless communications leveraging its unique advantages in the areas of RF, Mixed Signal/power management, monolithic integration and comprehensive know-how in cellular software and systems. Intel Mobile Communications targets the fast growing market segments of smart phones, connected devices (e.g., tablets, USB dongles, mobile PCs, M2M), and ultra-low-cost/entry phones. Its roadmap is focused to provide the most cost-effective 2G/3G single-chip platforms for ULC phones up to entry-level smart phones and to offer best-in-class 3G/4G slim modem and RF solutions for mid-to high-end smart phones and connected devices. Intel Mobile Communication has formerly been a division of Infineon Technologies AG, called Wireless Solutions (WLS). Early in 2011, Intel completed the acquisition of Infineon's wireless business that has more than 3,500 employees worldwide.

Intel, and the Intel logo are trademarks of Intel Corporation in the United States and other countries. * Other names and brands may be claimed as the property of others.

Source: Intel